

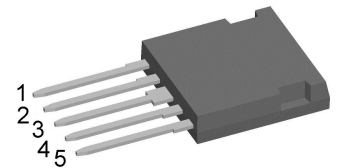
# HiPerFRED

$V_{RRM} = 1200\text{ V}$   
 $I_{DAV} = 30\text{ A}$   
 $t_{rr} = 40\text{ ns}$

High Performance Fast Recovery Diode  
 Low Loss and Soft Recovery  
 3~ Rectifier Bridge

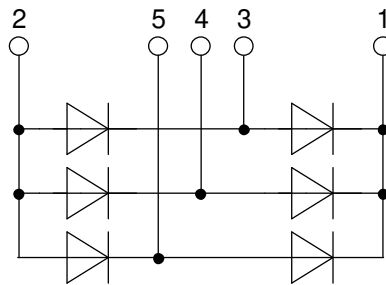
Part number

**FUE30-12N1**



Backside: isolated

 E72873



### Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low  $I_{rm}$ -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low  $I_{rm}$  reduces:
  - Power dissipation within the diode
  - Turn-on loss in the commutating switch

### Applications:

- Rectifiers in switch mode power supplies (SMPS)

### Package: i4-Pac

- Isolation Voltage: 3000 V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

### Disclaimer Notice

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at [www.littelfuse.com/disclaimer-electronics](http://www.littelfuse.com/disclaimer-electronics).

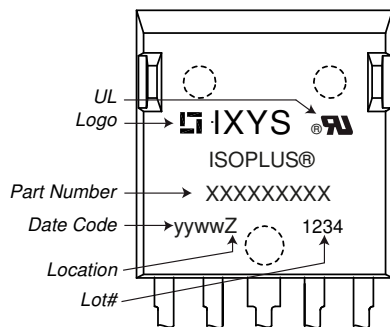


Fast Diode				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{RSM}$	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
$V_{RRM}$	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
$I_R$	reverse current, drain current	$V_R = 1200\text{ V}$	$T_{VJ} = 25^{\circ}C$		100	$\mu A$	
		$V_R = 1200\text{ V}$	$T_{VJ} = 150^{\circ}C$		0.5	mA	
$V_F$	forward voltage drop	$I_F = 10\text{ A}$	$T_{VJ} = 25^{\circ}C$		2.37	V	
		$I_F = 30\text{ A}$			3.17	V	
		$I_F = 10\text{ A}$	$T_{VJ} = 150^{\circ}C$		1.60	V	
		$I_F = 30\text{ A}$			2.54	V	
$I_{DAV}$	bridge output current	$T_C = 120^{\circ}C$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 175^{\circ}C$		30	A	
$V_{FO}$	threshold voltage	} for power loss calculation only	$T_{VJ} = 175^{\circ}C$		0.97	V	
$r_F$	slope resistance				48	m $\Omega$	
$R_{thJC}$	thermal resistance junction to case				2.3	K/W	
$R_{thCH}$	thermal resistance case to heatsink			0.2		K/W	
$P_{tot}$	total power dissipation		$T_C = 25^{\circ}C$		65	W	
$I_{FSM}$	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}; V_R = 0\text{ V}$	$T_{VJ} = 45^{\circ}C$		90	A	
$C_J$	junction capacitance	$V_R = 600\text{ V}$ $f = 1\text{ MHz}$	$T_{VJ} = 25^{\circ}C$		5	pF	
$I_{RM}$	max. reverse recovery current	} $I_F = 15\text{ A}; V_R = 600\text{ V}$ $-di_F/dt = 200\text{ A}/\mu\text{s}$	$T_{VJ} = 25^{\circ}C$		6	A	
			$T_{VJ} = 100^{\circ}C$		9	A	
$t_{rr}$	reverse recovery time		$T_{VJ} = 25^{\circ}C$		50	ns	
			$T_{VJ} = 100^{\circ}C$		140	ns	



Package i4-Pac		Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			50	A
$T_{VJ}$	virtual junction temperature		-55		175	°C
$T_{op}$	operation temperature		-55		150	°C
$T_{stg}$	storage temperature		-55		150	°C
<b>Weight</b>				6		g
$F_C$	mounting force with clip		20		120	N
$d_{Spp/ App}$	creepage distance on surface   striking distance through air	terminal to terminal	1.7			mm
$d_{Spb/ Apb}$		terminal to backside	5.1			mm
$V_{ISOL}$	isolation voltage	t = 1 second	3000			V
		t = 1 minute	2500			V

**Product Marking**



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	FUE30-12N1	FUE30-12N1	Tube	25	488690

**Equivalent Circuits for Simulation**

\* on die level

$T_{VJ} = 175^{\circ}C$



**Fast Diode**

$V_{0\ max}$	threshold voltage	0.97	V
$R_{0\ max}$	slope resistance *	46	mΩ

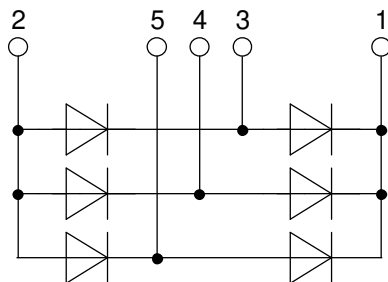


**Outlines i4-Pac**



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b2	1.47	1.73	0.058	0.068
b4	2.54	2.79	0.100	0.110
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	14.99	15.75	0.590	0.620
D2	1.65	2.03	0.065	0.080
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	16.76	17.53	0.660	0.690
e	3.81 BSC		0.150 BSC	
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite  
The convexbow of substrate is typ. < 0.05 mm over plastic surface level of device bottom side



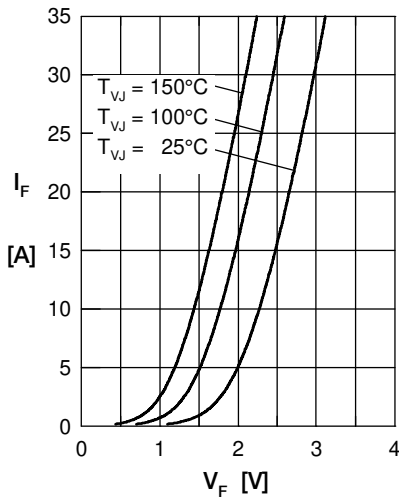
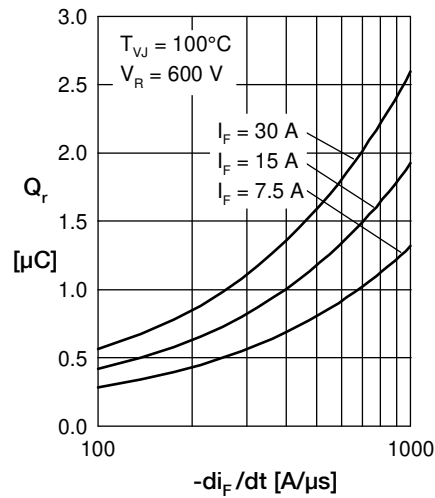
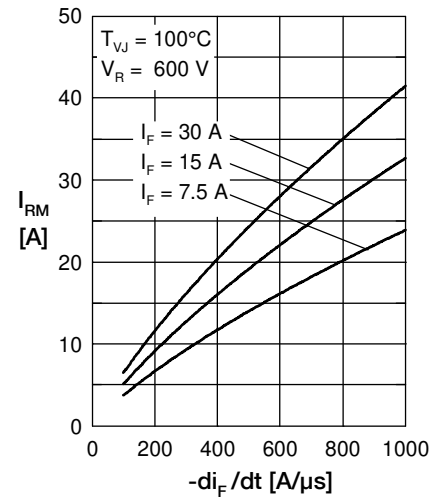
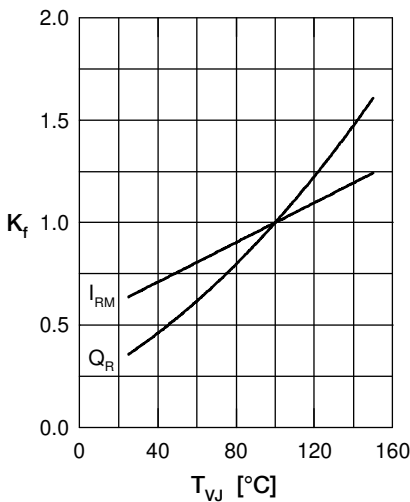
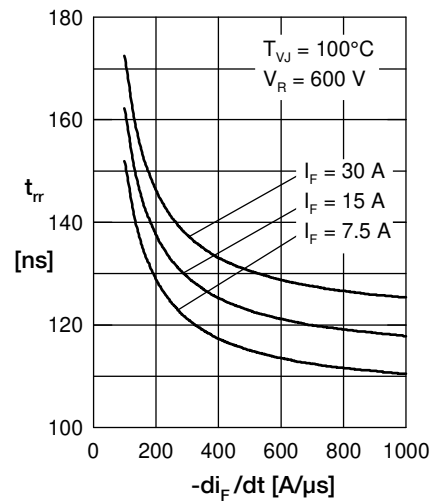
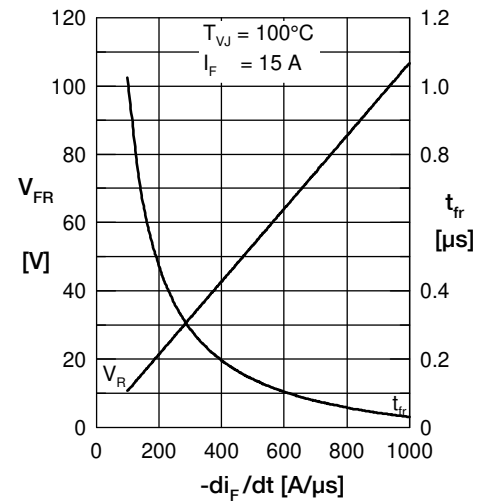
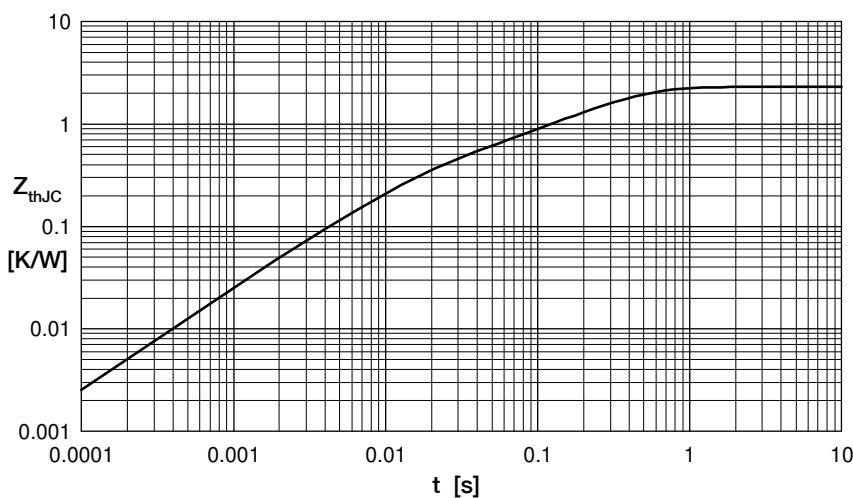
**Fast Diode**

 Fig. 1 Forward current  $I_F$  versus  $V_F$ 

 Fig. 2 Reverse recovery charge  $Q_r$  versus  $-di_F/dt$ 

 Fig. 3 Peak reverse current  $I_{RM}$  versus  $-di_F/dt$ 

 Fig. 4 Dynamic parameters  $Q_r$ ,  $I_{RM}$  versus  $T_{VJ}$ 

 Fig. 5 Recovery time  $t_{rr}$  versus  $-di_F/dt$ 

 Fig. 6 Peak forward voltage  $V_{FR}$  and  $t_{fr}$  versus  $di_F/dt$ 


Fig. 7 Transient thermal resistance junction to case

 Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.78545	0.0052
2	0.30245	0.0003
3	0.0621	0.0004
4	1.15	0.0092